



SLOVENSKI STANDARD SIST EN IEC 61967-1:2019

01-april-2019

Nadomešča:
SIST EN 61967-1:2005

Integrirana vezja - Meritve elektromagnetnega sevanja - 1. del: Splošni pogoji in definicije (IEC 61967-1:2018)

Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions (IEC 61967-1:2018)

Integrierte Schaltungen - Messung von elektromagnetischen Aussendungen - Teil 1: Allgemeine Bedingungen und Definitionen (IEC 61967-1:2018)

Circuits intégrés - Mesure des émissions électromagnétiques - Partie 1: Conditions générales et définitions (IEC 61967-1:2018)

Ta slovenski standard je istoveten z: EN IEC 61967-1:2019

ICS:

31.200	Integrirana vezja, mikroelektronika	Integrated circuits. Microelectronics
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SIST EN IEC 61967-1:2019

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EUROPEAN STANDARD

EN IEC 61967-1

NORME EUROPÉENNE

EUROPÄISCHE NORM

February 2019

ICS 31.200

Supersedes EN 61967-1:2002

English Version

Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions (IEC 61967-1:2018)

Circuits intégrés - Mesure des émissions
électromagnétiques - Partie 1: Conditions générales et
définitions
(IEC 61967-1:2018)

Integrierte Schaltungen - Messung von
elektromagnetischen Aussendungen - Teil 1: Allgemeine
Bedingungen und Definitionen
(IEC 61967-1:2018)

This European Standard was approved by CENELEC on 2019-01-16. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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SIST EN IEC 61967-1:2019

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61967-1:2019 (E)**European foreword**

The text of document 47A/1062/FDIS, future edition 2 of IEC 61967-1, prepared by SC 47A "Integrated circuits" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61967-1:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2019-10-16
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-01-16

This document supersedes EN 61967-1:2002.

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The text of the International Standard IEC 61967-1:2018 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61967-2	NOTE	Harmonized as EN 61967-2
IEC 61967-4	NOTE	Harmonized as EN 61967-4
IEC 61967-5	NOTE	Harmonized as EN 61967-5
IEC 61967-6	NOTE	Harmonized as EN 61967-6
IEC 61967-8	NOTE	Harmonized as EN 61967-8
IEC 62132-1	NOTE	Harmonized as EN 62132-1
CISPR 25:2008	NOTE	Harmonized as EN 55025:2008 (not modified)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
CISPR 16-1-1	-	Specification for radio disturbance and immunity measuring apparatus and Methods - Part 1-1: Radio disturbance and immunity measuring apparatus - Measuring apparatus	EN 55016-1-1	-

[SIST EN IEC 61967-1:2019](https://standards.iteh.ai/catalog/standards/sist/69b0197d-4866-4f25-aa13-fd42a5c1a4d5/sist-en-iec-61967-1-2019)
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IEC 61967-1

Edition 2.0 2018-12

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Integrated circuits – Measurement of electromagnetic emissions –
Part 1: General conditions and definitions**

**Circuits intégrés – Mesure des émissions électromagnétiques –
Partie 1: Conditions générales et définitions**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 31.200

ISBN 978-2-8322-6284-9

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**INTEGRATED CIRCUITS –
MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –****Part 1: General conditions and definitions**

FOREWORD

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International Standard IEC 61967-1 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) the frequency range of 150 kHz to 1 GHz has been deleted from the title;
- b) the frequency step above 1 GHz has been added to Table 1, Table 2 and to 5.4;
- c) Table A.1 has been divided into two tables, and IEC 61967-8 has been added to Table A.2 of Annex A;
- d) the general test board description has been moved to Annex D.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47A/1062/FDIS	47A/1066/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61967 series, under the general title *Integrated circuits – Measurement of electromagnetic emissions*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTEGRATED CIRCUITS – MEASUREMENT OF ELECTROMAGNETIC EMISSIONS –

Part 1: General conditions and definitions

1 Scope

This part of IEC 61967 provides general information and definitions on the measurement of conducted and radiated electromagnetic disturbances from integrated circuits. It also provides a description of measurement conditions, test equipment and set-up as well as the test procedures and content of the test reports. Test method comparison tables are included in Annex A to assist in selecting the appropriate measurement method(s).

The object of this document is to describe general conditions in order to establish a uniform testing environment and to obtain a quantitative measure of RF disturbances from integrated circuits (IC). Critical parameters that are expected to influence the test results are described. Deviations from this document are noted explicitly in the individual test report. The measurement results can be used for comparison or other purposes.

Measurement of the voltage and current of conducted RF emissions or radiated RF disturbances, coming from an integrated circuit under controlled conditions, yields information about the potential for RF disturbances in an application of the integrated circuit.

The applicable frequency range is described in each part of IEC 61967.

[SIST EN IEC 61967-1:2019](https://standards.iteh.ai/catalog/standards/sist/69b0197d-4866-4f25-aa13-fd42a5c1a4d5/sist-en-iec-61967-1-2019)

2 Normative references

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The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

CISPR 16-1-1, *Specification for radio disturbance and immunity measuring apparatus and Methods – Part 1-1: Radio disturbance and immunity measuring apparatus – Measuring apparatus*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

artificial network

AN

network presenting a reference load impedance (simulated) to the DUT (e.g. extended power or communication lines) across which the RF disturbance voltage is measured and which isolates the apparatus from the power supply or loads in a given frequency range